

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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Assignment ID: PATI330330

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Don Banfield	06/27/2024
<b>RECEIVING PARTY DATA</b>	
<b>Company Name:</b>	Cornell University
<b>Street Address:</b>	Center for Technology Licensing
<b>Internal Address:</b>	395 Pine Tree Road, Suite 210
<b>City:</b>	Ithaca
<b>State/Country:</b>	NEW YORK
<b>Postal Code:</b>	14850
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17144097
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	166118.01029.T002403
<b>NAME OF SUBMITTER:</b>	Chris Holzer
<b>SIGNATURE:</b>	Chris Holzer
<b>DATE SIGNED:</b>	06/28/2024
<b>Total Attachments: 1</b>	
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T002403

### ASSIGNMENT

WHEREAS, the undersigned have made certain inventions which are described in **U.S. Utility Patent Application Number 17/144,097**, filed January 7, 2021, entitled *Systems and Methods for Operation of a Sonic Anemometer*, which claims the benefit of U.S. Provisional Patent Number 62/958,030, filed January 7, 2020, entitled *Flow Testing of a Sonic Anemometer for the Martian Environment*; and

WHEREAS, **Cornell University** (herein referred to as the Company), having a place of business at **Center for Technology Licensing, 395 Pine Tree Road, Suite 210, Ithaca, New York 14850** is desirous of acquiring the interest in said invention throughout the United States of America and the territories thereof, for all other countries and under all international agreements,

NOW, THEREFORE, for and in consideration of One Dollar (\$1.00), and other good and valuable consideration, receipt whereof is hereby acknowledged, the undersigned hereby sell(s), assign(s) and transfer(s) unto said Company, its successors and assigns, the entire right, title and interest throughout the United States of America and the territories thereof, for all foreign countries and under all international agreements in and to said inventions, the aforesaid application, all other applications hereafter filed in the United States, in any other country, or under any international agreement based in whole or in part on said inventions, and all Letters Patents granted upon said applications by the United States, by any other country or under any international agreement, and do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said Companies.

The undersigned further grant to said Company, its successors and assigns, the right to claim for any of said applications the full benefits and priority rights of any international agreement between the United States and any foreign country or countries of between any other countries. The undersigned hereby warrant(s) that they/(s)he have/has the full right to make the conveyance herein, and hereby covenant(s) that the heirs, legal representatives and assigns of the undersigned, will when requested, communicate to said Company, its representatives, successors and assigns, all facts known respecting said inventions, execute all divisional, continuing, reissue, reexamination and foreign or international applications, together with individual assignment therefore, make all rightful oaths, sign all lawful papers, testify in any legal proceeding and generally do everything possible to aid said Company, its successors and assigns, in the obtaining of Letters Patent.

IN TESTIMONY WHEREOF, the undersigned have hereunto executed this assignment at the location and on the date indicated below.

**Inventor: Don Banfield**

DocuSigned by:  
  
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Inventor Signature

6/27/2024  
Date of Signature